



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



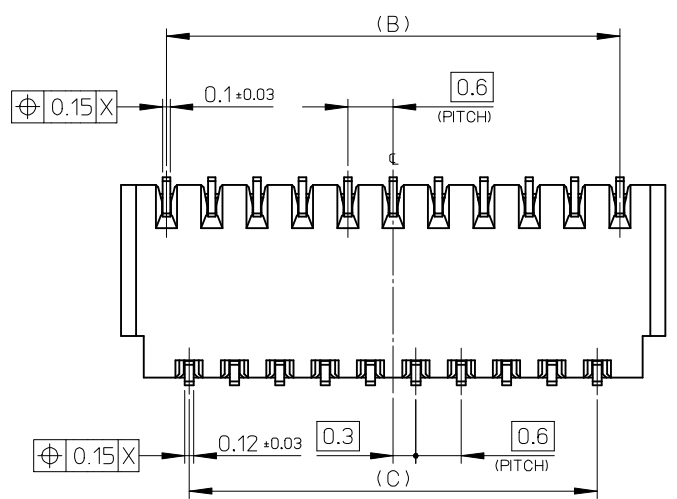
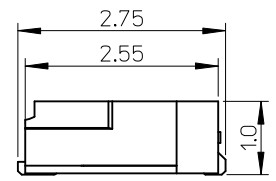
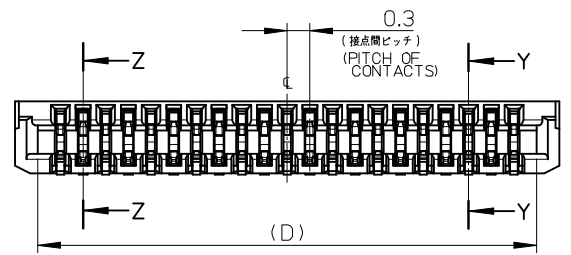
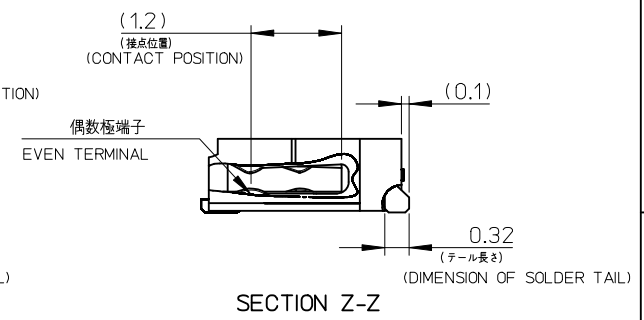
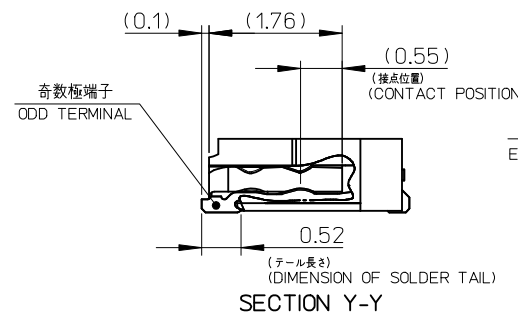
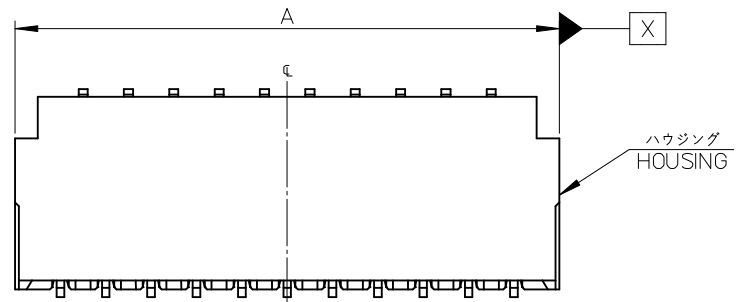
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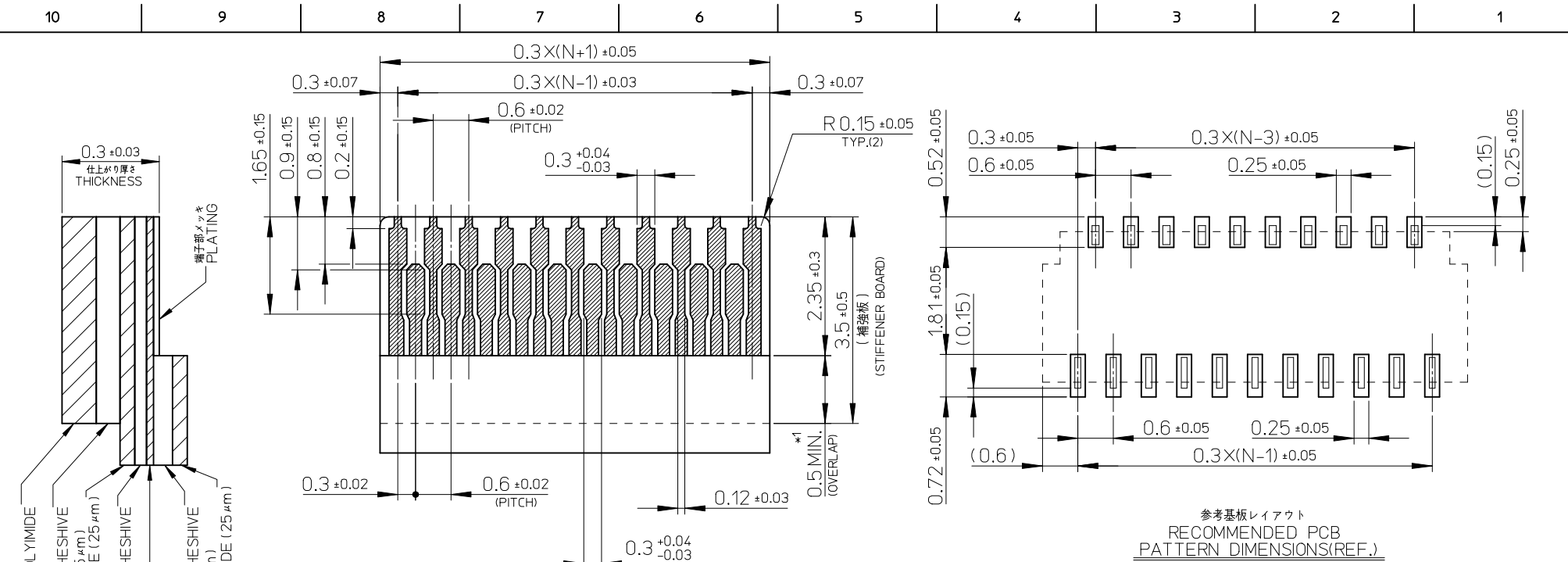


注記 NOTES

- 使用材料 MATERIAL
 ハウジング: 液晶ポリマー(LCP)、ナチュラル(白色系)、ガラス充填、UL94V-0
 奇数端子: 燐青銅、ニッケル下地、金メッキ
 偶数端子: 燐青銅、ニッケル下地、金メッキ
 HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL(WHITE)
 ODD TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
 EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- めっき仕様 PLATING
 ターミナル TERMINAL
 接点部: 金メッキ 0.1μm以上
 テール部: 金メッキ
 下地: ニッケルメッキ 1.0μm以上
 CONTACT AREA: GOLD PLATING 0.1μm MINIMUM
 TAIL AREA: GOLD PLATING
 UNDER PLATING: NICKEL PLATING 1.0μm MINIMUM
- 端子のコプラナリティーは 0.1 以下とする。
 COPLANALITY OF SOLDER TAILS: 0.1MAX.
- ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT
- 一般公差: ±0.3
 GENERAL TOLERANCE: ±0.3

6.0	4.8	5.4	6.6	504281-1900	19
5.4	4.2	4.8	6.0	504281-1700	17
4.2	3.0	3.6	4.8	504281-1300	13
3.6	2.4	3.0	4.2	504281-1100	11
D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUIT

RELEASED EC NO.: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07 REV: O	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER ±0.2		DRAWN BY NNISHI		DATE 2012/07/17		TITLE 0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM			
	10 OVER 30 UNDER ±0.25		CHECKED BY HIJIMA		DATE 2012/07/17		molex SD-504281-001			
	30 OVER ±0.3		APPROVED BY YNOGAWA		DATE 2014/05/07					
	ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3								



補強板: ポリイミド
STIFFENER BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25µm)
BASE FILM: POLYIMIDE (25µm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35µm)
COPPER FOIL (35µm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25µm)
COVER FILM: POLYIMIDE (25µm)

FPC構成推奨仕様
STRUCTURE OF FPC

適合するFPC推奨寸法 (参考)
APPLICABLE FPC
PATTERN DIMENSIONS(REF.)
(端子仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS(REF.)

推奨ペースト厚: 100µm
推奨マスク開口率: 80%
RECOMMEND SCREEN THICKNESS: 100µm
RECOMMEND SCREEN OPEN RATIO: 80%

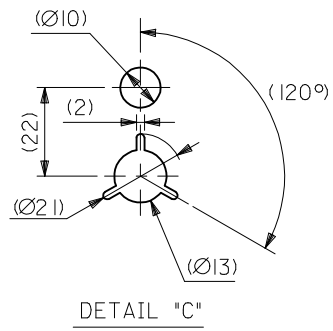
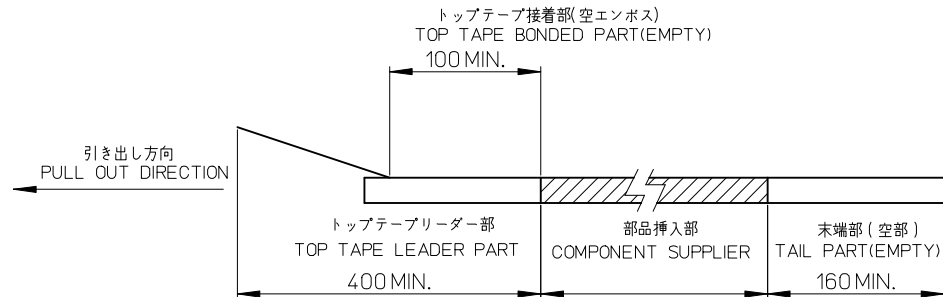
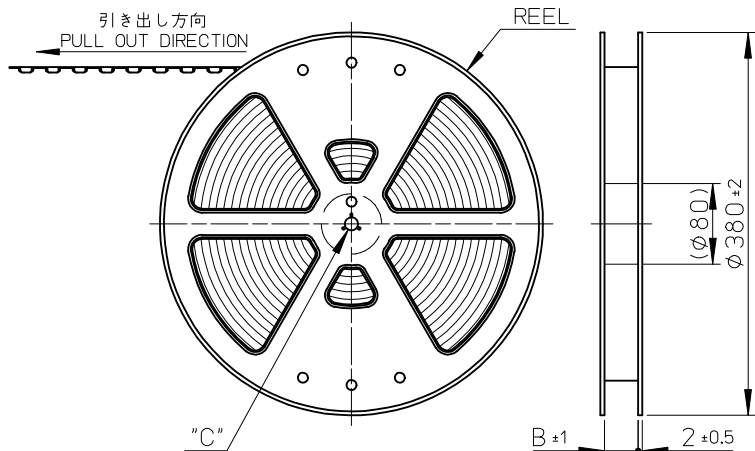
・FPCについて (ABOUT FPC)
抜き方向は、導体側から補強板側を推奨します。
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は同通不良の原因となりますので、
染み出しが無い様お願いします。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様 (FPC PATTERN PLATING)
金メッキ: 0.1µm以上
下地ニッケルメッキ: 2~6µm
GOLD PLATING: 0.1µm MINIMUM
NICKEL UNDER PLATING: 2~6µm
*1 補強板長さが図面通り確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を0.5mm以上として下さい。
WHEN STIFFENER BOARD DIMENSION CAN NOT
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	+0.2	DRAWN BY NNISHI	DATE 2012/07/17	TITLE 0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM	
	10 OVER	±0.25	CHECKED BY HIJIMA	DATE 2012/07/17		
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/05/07		
0	ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-504281-001	SHEET NO. 2 OF 2	
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

注記 NOTES

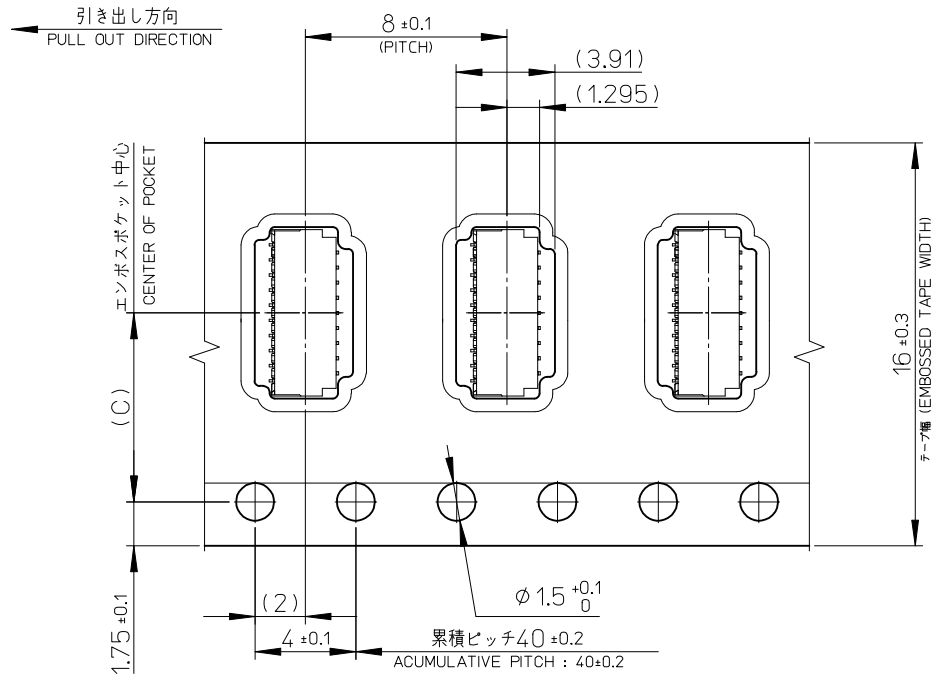
- 製品詳細寸法については図面SD-504281-001を参照下さい。
CONNECTOR DETAILED DIMENSIONS, REFER TO SD-504281-001.
- 梱包数量: 5000個/リール
NUMBER OF CONNECTORS : 5000PCS / REEL
- リードテープ長さ
LEAD TAPE LENGTH



- キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE) : PET, PE, PEF
リール(REEL) : ポリスチレン(POLYSTYRENE) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剝離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3

RELEASED EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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	10 OVER 30 UNDER	±0.25	CHECKED BY HIJIMA	DATE 2013/05/20		
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/05/07		
ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-504281-002	SHEET NO. 1 OF 2		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



7.5	17.4	6.6	504281-1900	19
		6.0	504281-1700	17
		4.8	504281-1300	13
		4.2	504281-1100	11
C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	種 教 CkT.

SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN:SKUROSE 2014/04/28 CHKD:H I J I M A 2014/04/28 APPR:YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SKUROSE	DATE 2013/05/20	TITLE 0.3 FPC CONN NON-ZIF TYPE HGT=1.0MM	
	10 OVER 30 UNDER	±0.25	CHECKED BY H I I J I M A	DATE 2013/05/20	molex	
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/05/07		
	ANGULAR	±1 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1	SD-504281-002		2 OF 2	

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

9 8 7 6 5 4 3 2